

L Number	Hits	Search Text	DB	Time stamp
1	1620	(dmd or (digital adj micro adj mirror adj device)) and (method or process or steps)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 13:05
2	393	((dmd or (digital adj micro adj mirror adj device)) and (method or process or steps)) and (singulating or cut or slice or dice or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 12:54
3	7243	hygroscopicity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 12:54
4	3	((dmd or (digital adj micro adj mirror adj device)) and (method or process or steps)) and hygroscopicity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 12:54
5	1677	(dmd or (digital adj micro adj (mirror or device))) and (method or process or steps)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 14:11
6	11	((dmd or (digital adj micro adj (mirror or device))) and (method or process or steps)) and ((adhesive with solder) or (solder with (chip or (base or substrate))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 13:52
7	2	5936758.URPN.	USPAT	2002/04/24 13:52
8	10	((dmd or (digital adj micro adj (mirror or device))) and (method or process or steps)) and (wafer with (metal adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 13:53
9	10	((dmd or (digital adj micro adj (mirror or device))) and (method or process or steps)) and (wafer with ((metallic or metal) adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 13:54
10	0	20010041381.URPN.	USPAT	2002/04/24 13:57
11	0	20010041381.URPN.	USPAT	2002/04/24 13:57
12	0	20010041381.URPN.	USPAT	2002/04/24 13:57
13	7	("4253231" "5189578" "5479695" "5724015" "5852866" "5867347" "5959808").PN.	USPAT	2002/04/24 13:59
14	2308	(dmd or (digital adj micro adj (mirror or device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 14:53
15	18	((dmd or (digital adj micro adj (mirror or device)))) and ((metal or meatllic) with back\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 14:14
16	17	((dmd or (digital adj micro adj (mirror or device)))) and ((metal or meatllic) with back)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 14:14
18	2	((dmd or (digital adj micro adj (mirror or device)))) and ((metal or metallic) same lapped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/04/24 14:17

17	23	((dmd or (digital adj micro adj (mirror or device)))) and ((metal or metallic) with back)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:38
19	9	((dmd or (digital adj micro adj (mirror or device)))) and LAPPING	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:40
20	3	(dmd or (digital adj micro adj (mirror or device)))	IBM_TDB	2002/04/24 14:52
21	0	438/460.ccls. and (dmd or (digital adj micro adj (mirror or device)))	IBM_TDB	2002/04/24 14:42
22	1	438/460.ccls. and (dmd or (digital adj micro adj (mirror or device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:45
23	2	5817569.URPN.	USPAT	2002/04/24 14:43
24	6	438/460.ccls. and (chip with mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:45
25	780657	(dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:54
26	4414	(dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:54
27	870	((dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)) and (method or fabricate or process or step) and (cut or slice or scribe or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:56
28	52	((dmd or (digital adj micro adj (mirror or device)))) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 14:58
29	55	((dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)) and (method or fabricate or process or step) and (cut or slice or scribe or saw) and break and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 15:41
30	1	((dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)) and (metallic adj adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 15:36
31	6	((dmd or (digital adj micro adj (mirror or device))) or (chip with mirror)) and (metal near adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 15:37
32	213	metallic adj adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 15:55
33	0	2001237334.URPN.	USPAT	2002/04/24 15:48
34	5272	wafer with ((metallic or metal) near (layer or sheet or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/24 15:58

35	1737	438/\$.cccls. and (wafer with ((metallic or metal) near (layer or sheet or film)))	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2002/04/24 16:13
36	292	(438/\$.cccls. and (wafer with ((metallic or metal) near (layer or sheet or film)))) and ((metal or metallic) with (back or rear))	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2002/04/24 17:11
37	2994	257/\$.cccls. and ((metal or metallic) with (back or rear))	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2002/04/24 17:12
38	949	(257/\$.cccls. and ((metal or metallic) with (back or rear))) and wafer	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2002/04/24 17:14